

TGF250

Leader Tech's TGF250 series is a new type of thermal gap filler with ultra-high thermal conductivity and ultra-low thermal resistance. It is manufactured by an advanced arrangement technology so that the high thermal conductivity fillers are uniformly and vertically aligned and distributed into the polymer matrix, which can greatly increase the heat transfer efficiency. The low filler loading also makes the material possess good mechanical properties and excellent thermal stability. It can be used in a wide range of electronic fields with high requirements for heat dissipation.

Features:

- Soft
- Excellent compression performance
- Low thermal resistance
- Lightweight
- Excellent thermal stability property
- RoHS and Halogen Compliant

Applications:

- Satellite
- Radar
- Large Servers
- Data processing center
- High performance mobile phone, etc.

Storage Conditions:

- Store in the darkness
- Storage Temperature: ≤ 30 °C
- Storage Humidity: $\leq 70\%$
- When stacking the parts, the parts should not be higher than 7 layers or more than 1mm

Shelf Life:

- Stored at storage conditions: Two years
- Stored in unqualified storage conditions: 6 months

Properties:

Item	Parameter	Unit	Test Method
Color	Black	-	Visual
Specification	150*150	mm	ASTM D5947
Thickness	0.3 ~ 3	mm	ASTM D374
Hardness	55(±10)	Shore 00	ASTM D2240
Density	2.5(±0.2)	g/cc	ASTM D792
Tensile Strength	≥0.1	Mpa	ASTM D412
Elongation	≥30	%	ASTM D412
Tear Strength	≥0.3	N/mm	ASTM D624
Compression Ratio	≥25(@50PSI)	%	ASTM D695
UL Certification	V-0	-	UL94
Operating Temperature	-50 ~ 180	°C	IEC 600068-2-14

Thermal Characteristics:

Thermal Conductivity	25±5	W / m·K	ASTM D5470
Thermal Resistance	≤0.11(@20PSI/1mm)	°Cin ² /W	ASTM D5470